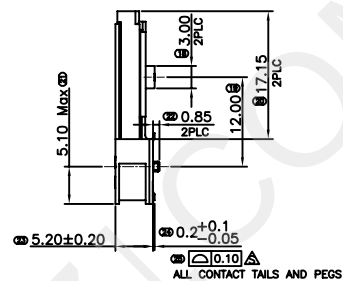
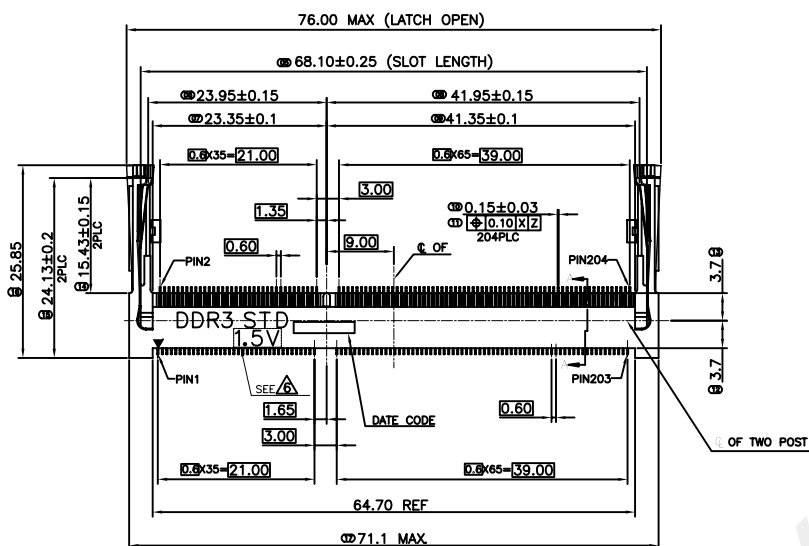
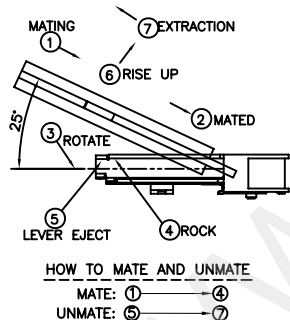


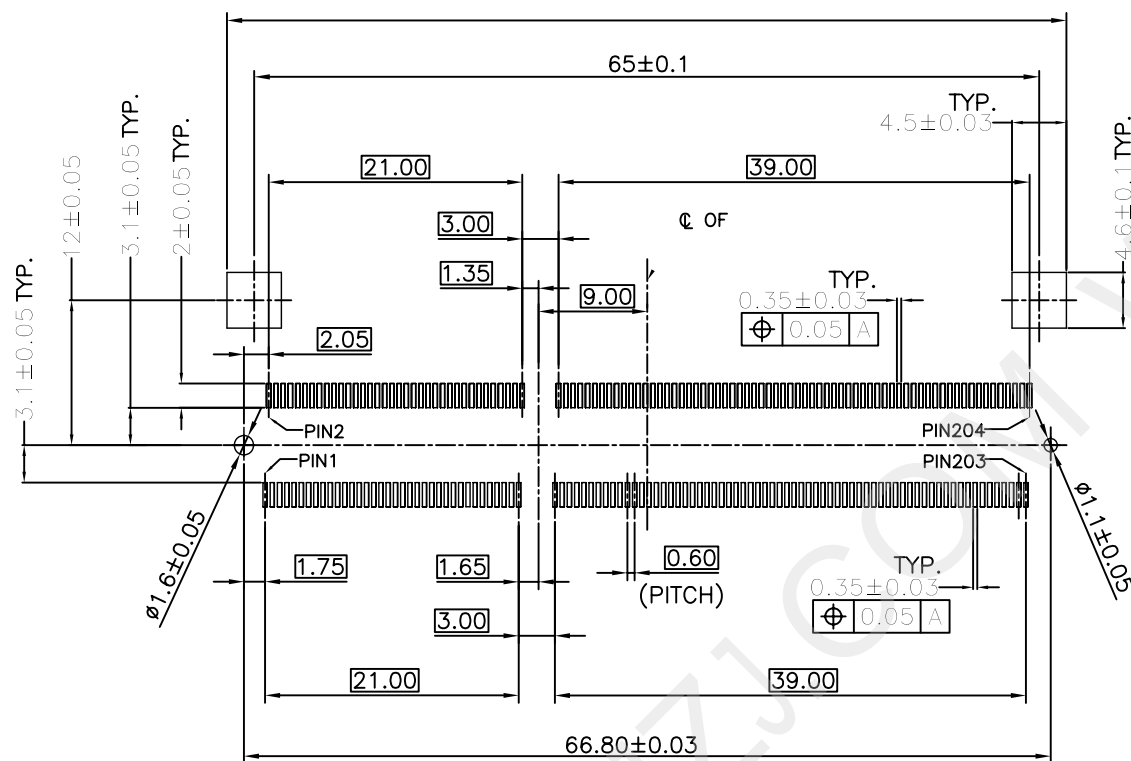
SECTION A-A
SCALE 2:1



- NOTES:
1. MATERIAL:
 - 1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0;
COLOR: BLACK.
 - 1.2 CONTACTS: COPPER ALLOY
 - 1.3 LATCH: STAINLESS STEEL
 - 1.4 FLOATING PEG: STAINLESS STEEL
 2. FINISH:
 - 2.1 CONTACT:
GOLD FLASH PLATED ON CONTACT AREA AND GOLD 2u"
SOLDER AREA. 50u" MIN. NICKEL UNDERPLATING.
 - 2.2 FLOATING PEG:
GOLD FLASH PLATED ON SOLDERING AREA.
50u" MIN. NICKEL UNDERPLATING.
 3. REFLOW SOLDER CAPABLE TO 260°C.
 4.  SHOULD BE MEASURED BY CPK
 5.  DIMENSIONS NEED BE CONTROLLED IN FAI.



		深圳市华宇创精密电子有限公司			
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2° X.X* ±0.5°		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: DDR3 5.2H 正向	
 UNIT: mm [inch]		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC20-DDR3-520S
		APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
SCALE:1:1	SIZE: A4	DRAW NO: HYC-2207041314			
		SHEET NO. 1 OF 1			



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X." ±2" X.X" ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

DDR3 5.2H 正向

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC20-DDR3-520S

MOLD NO.

APPROVED BY:

邱敏

DATE :

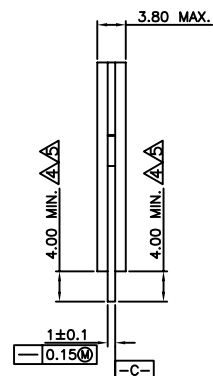
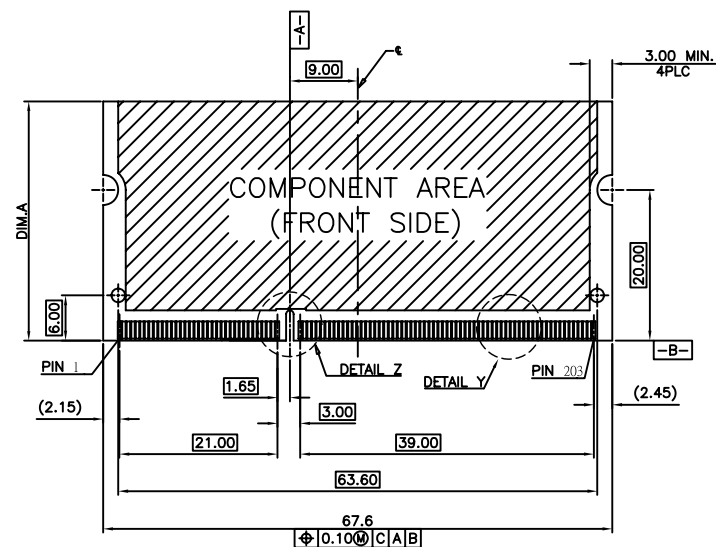
2014-02-23

DRAW NO:

HYC-2207041314

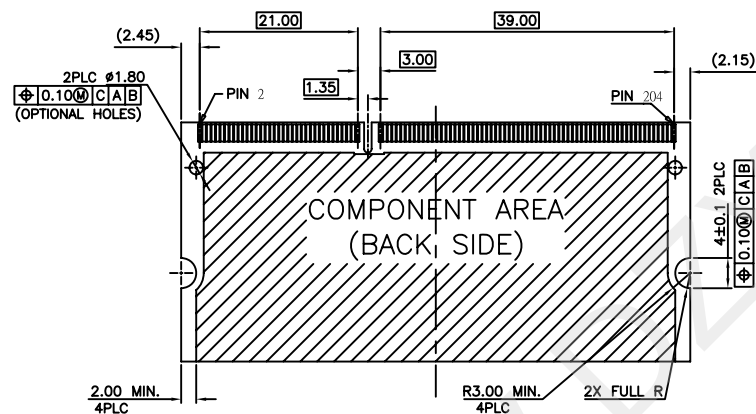
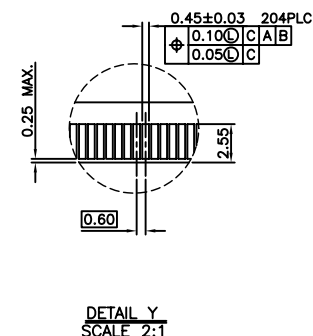
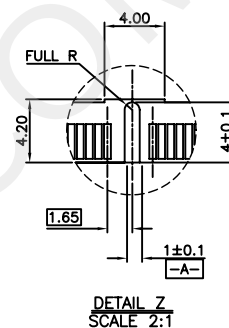
SHEET NO.

1 OF 1



NOTE:

- NOTE:
1. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
 2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAZATION.
 3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER ON PLATING 0.002MIN.
 4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE. PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
 5. BORDER OF COMPONENT AREA.
 6. REFER TO JEDEC SPEC. MO-268 FOR COMPLETE MODULE.



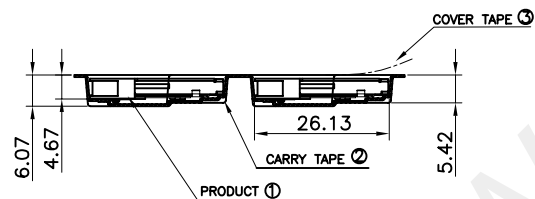
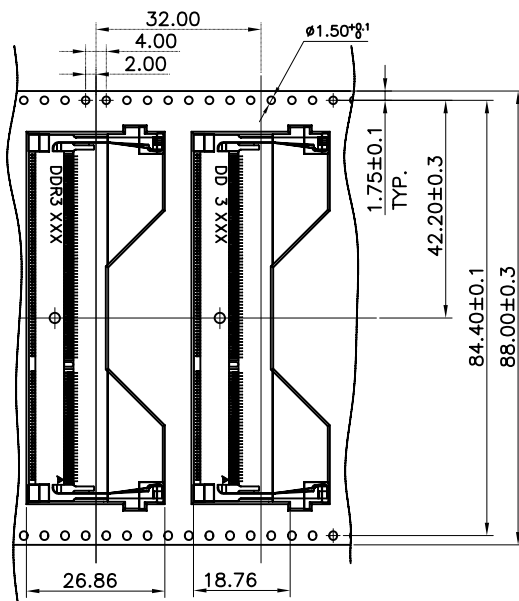
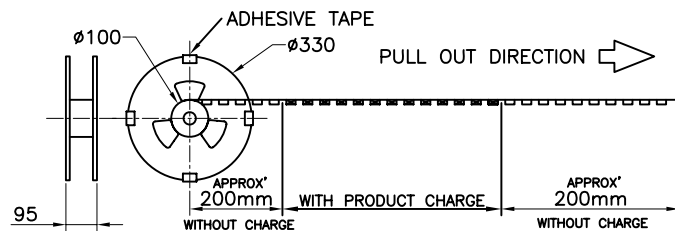
RECOMMENDED MATING P.C.B CONFIGURATION

30.00	CA
31.75	BA
25.40	AA
DIM. A	SDRAM VARIATIONS



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*				DDR3 5.2H 正向	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC20-DDR3-520S
		马跃	2014-02-23	MOLD NO.	
SCALE:1:1 SIZE: A4		APPROVED BY:	DATE :	DRAW NO:	HYC-2207041314
		邱敏	2014-02-23	SHEET NO.	1 OF 1



4.320KG	2.195KG	250	2
GROSS WEIGHT	NET WEIGHT	PCS/ REEL	REEL/ CARTON

NOTES : (FOR TAPE & REEL)

PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT MUST MEET DEREN CONTROLLED SUBSTANCES SPEC.

* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED:5 PPM.

* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED: 100 PPM (COMBINED).

* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.

1. MATERIAL :

COVER TAPE : ANTISTATIC P.S, COLOR: TRANSPARENT COLOR.

CARRIER TAPE : POLYSTYRENES.

REEL : POLYSTYRENES.

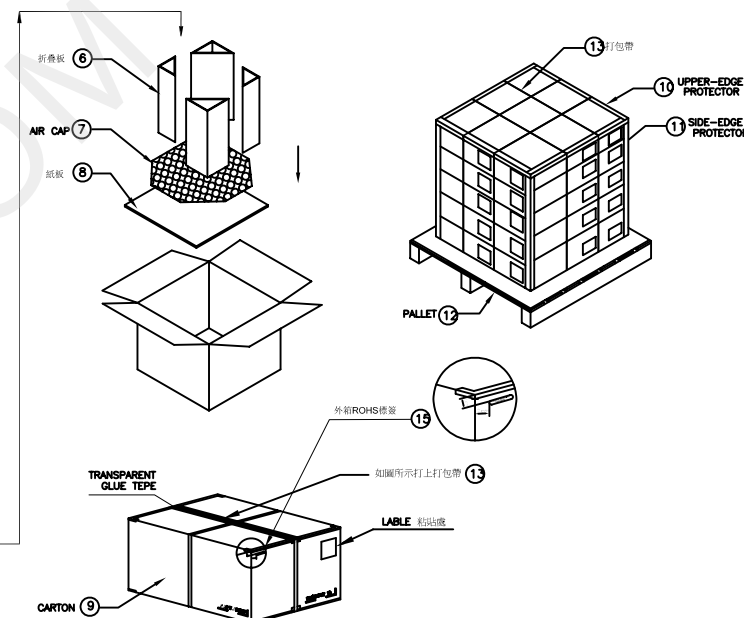
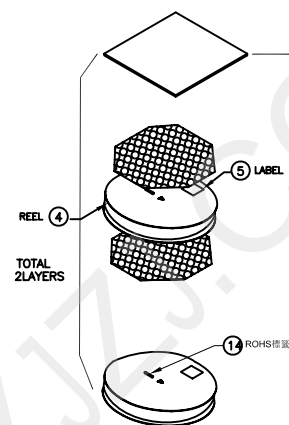
CARTON: CORRUGATED FIBER.

2. QUANTITY : SEE TABLE

3. WEIGHT : SEE TABLE

4. PEELING RESISTANCE : 10gf~100gf (for 8mm)
10gf~130gf (for 12mm~56mm)
10gf~150gf (for 72mm)

5. PEELING SPEED : 300mm/MINUTES



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X' ±2' X.X' ±0.5'

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

包装图

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

SHEET NO.

1 OF 1